

# **Japan TC Chapter 3D Packaging & Integration (3DP&I) Global Technical Committee**

**Liaison Report | June 2021**

**V1.1**

# Meeting Information

- Last meeting
  - Friday, May 28, 2021 at the SEMI Standards Japan Spring Meetings
    - Web Conference
- Next meeting
  - Friday, October 22, 2021
    - Web Conference

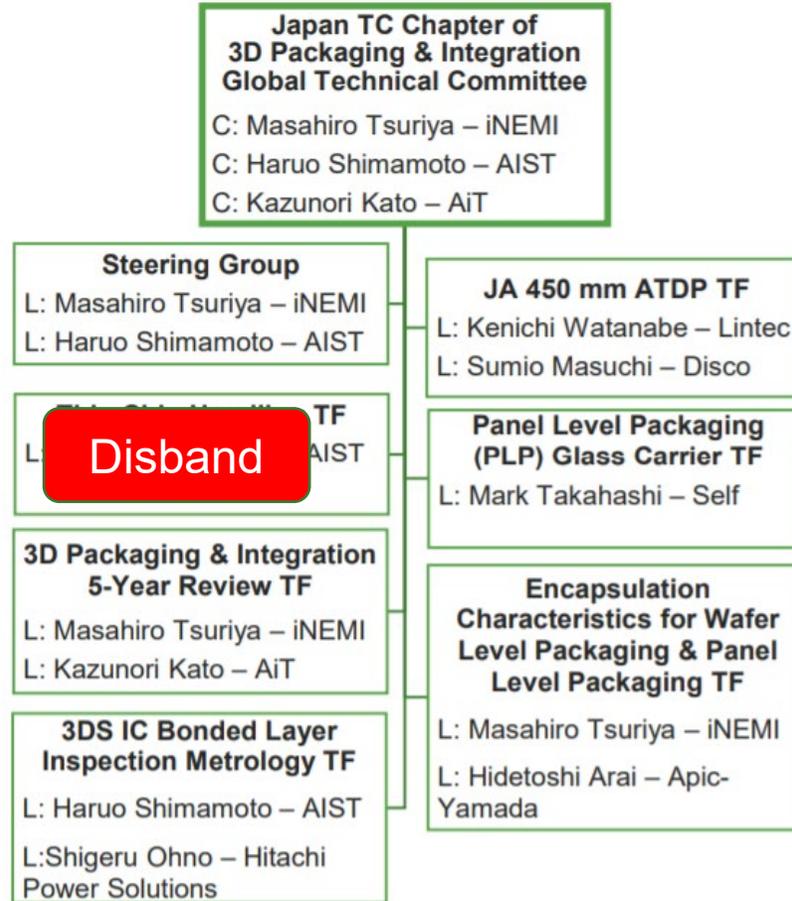
<http://www.semi.org/en/standards-events>

# Committee Structure Changes



| Previous WG/TF/SC Name | New WG/TF/SC Name or Status Change |
|------------------------|------------------------------------|
| Thin Chip Handling TF  | Disband                            |

# Organization Chart



# Ballot Results



| Doc # | Document Title  | TC Chapter Action  |
|-------|---|--|
| 6703  | Revision to SEMI G63-95 (Reapproved 0811) “Test Method for Measurement of Die Shear Strength” | <b>Failed</b> due to insufficient rate and return to TF for rework |

Note 1: **Passed** ballots and line items will be submitted to the ISC Audit & Review Subcommittee for procedural review.

Note 2: **Failed** ballots and line items were returned to the originating task forces for re-work and re-balloting or abandoning.

# Authorized Ballots



| Doc # | When           | TF  | Document Title/Details  |
|-------|----------------|---|---|
| 6703A | Cycle 8/9-2021 | 3D Packaging & Integration 5 Year Review TF | Revision to SEMI G63-95 (Reapproved 0811) "Test Method for Measurement of Die Shear Strength" |

# Task Force Highlights[1/3]



- Encapsulation Characteristics for Wafer Level Package and Panel Level Packaging TF
  - Taskforce Kick-off: November 18, 2020
  - Under development of standard document drafts for 8 encapsulate materials characteristics and 3 items for performances
  - SNARFs approval requests for 8 material characteristics
    - Ballot6706,6707,6708,6709,6710,6711,6712
  - Plan to develop final ballot draft by the end of Q3.
- Panel Level Packaging (PLP) Glass Carrier TF
  - Reviewed ballot 6590, New Standard: Specification for Glass Carrier Characteristics for Panel Level Packaging (PLP) Applications

# Task Force Highlights[2/3]



- Five Years Review TF
  - Completed the review and submitted the ballots for 2020 required review documents.
  - Will start for 2021 review needed
- 3DS IC Bonded Layer Inspection Metrology TF
  - Pre-trial using the SEMATECH sample was done by Aug. 2020.
  - Detectable void size by the nominal frequency of the transducer was defined.
  - A sample for the feasibility study was designed by Sept. 2020.
  - Manufacturing the sample for the feasibility study is delayed due to COVID and equipment trouble.

# Task Force Highlights[3/3]



- 3D Packaging & Integration Steering Group WG
  - Continue to brainstorm the potential areas of SEMI Standard.
    - Example: RDL Adhesion Strength Measurement/Metrology Proposal
  - Share the taskforce activities progress
  - Work on the joint discussion with TWN TC (held meeting on August 2020)
  - Displayed 3 posters at SEMICON Japan 2020

# Thank you!

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